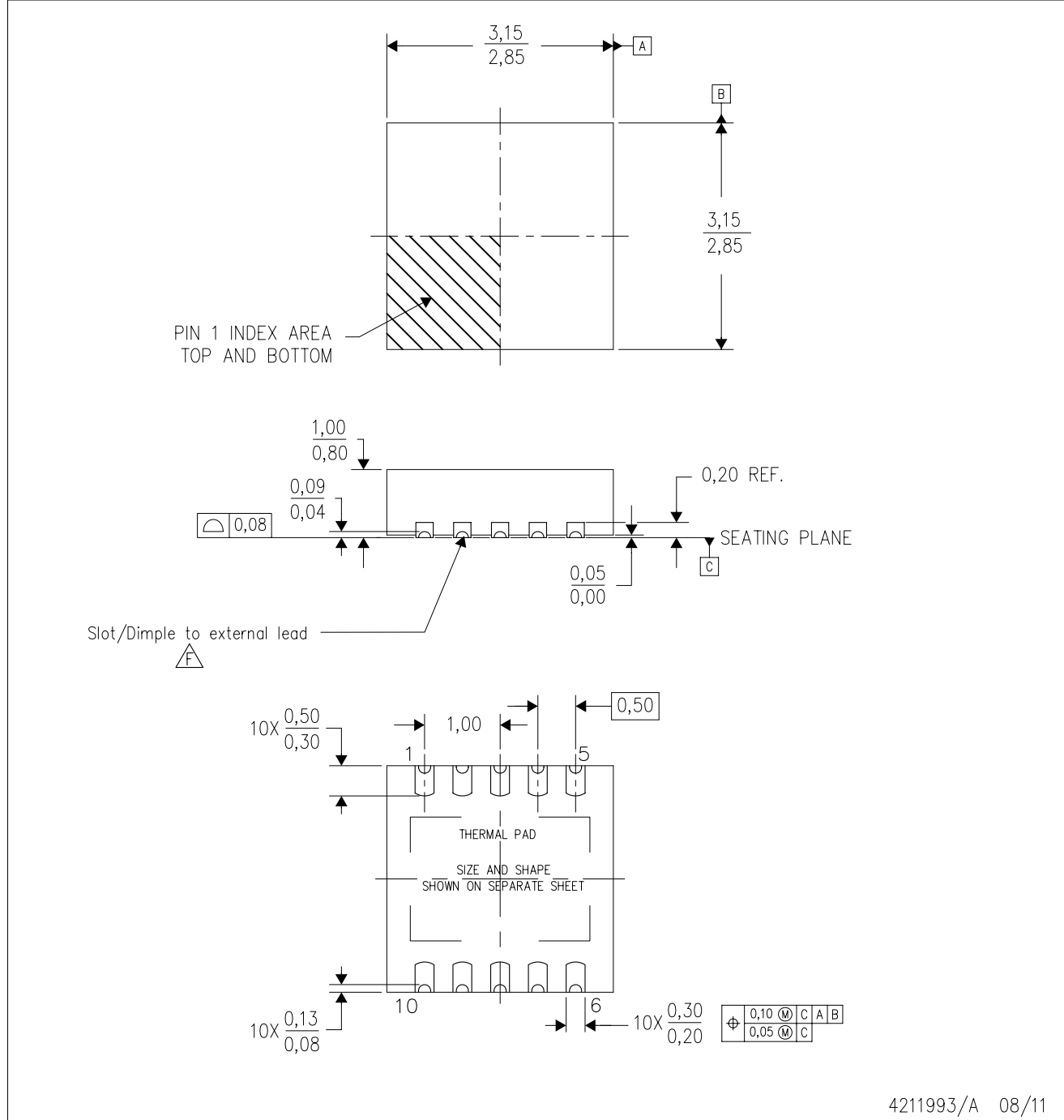


DPN (S-PVSON-N10)

PLASTIC SMALL OUTLINE NO-LEAD



- NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 B. This drawing is subject to change without notice.
 C. Small Outline No-Lead (SON) package configuration.
 D. The package thermal pad must be soldered to the board for thermal and mechanical performance, if present.
 E. See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
 F. Slot/Dimple added to external leads.

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